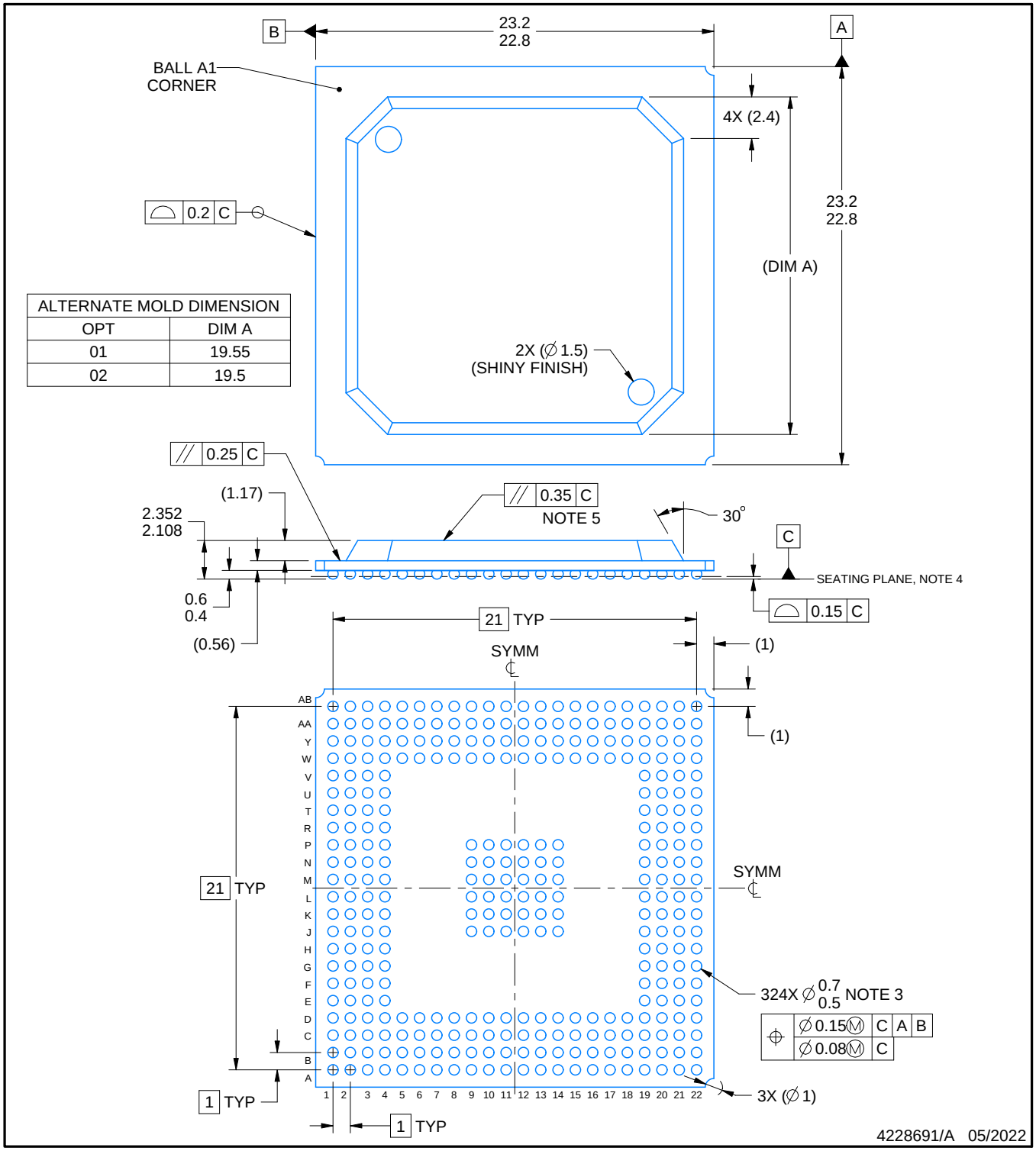
PACKAGE OUTLINE

ZDQ0324A

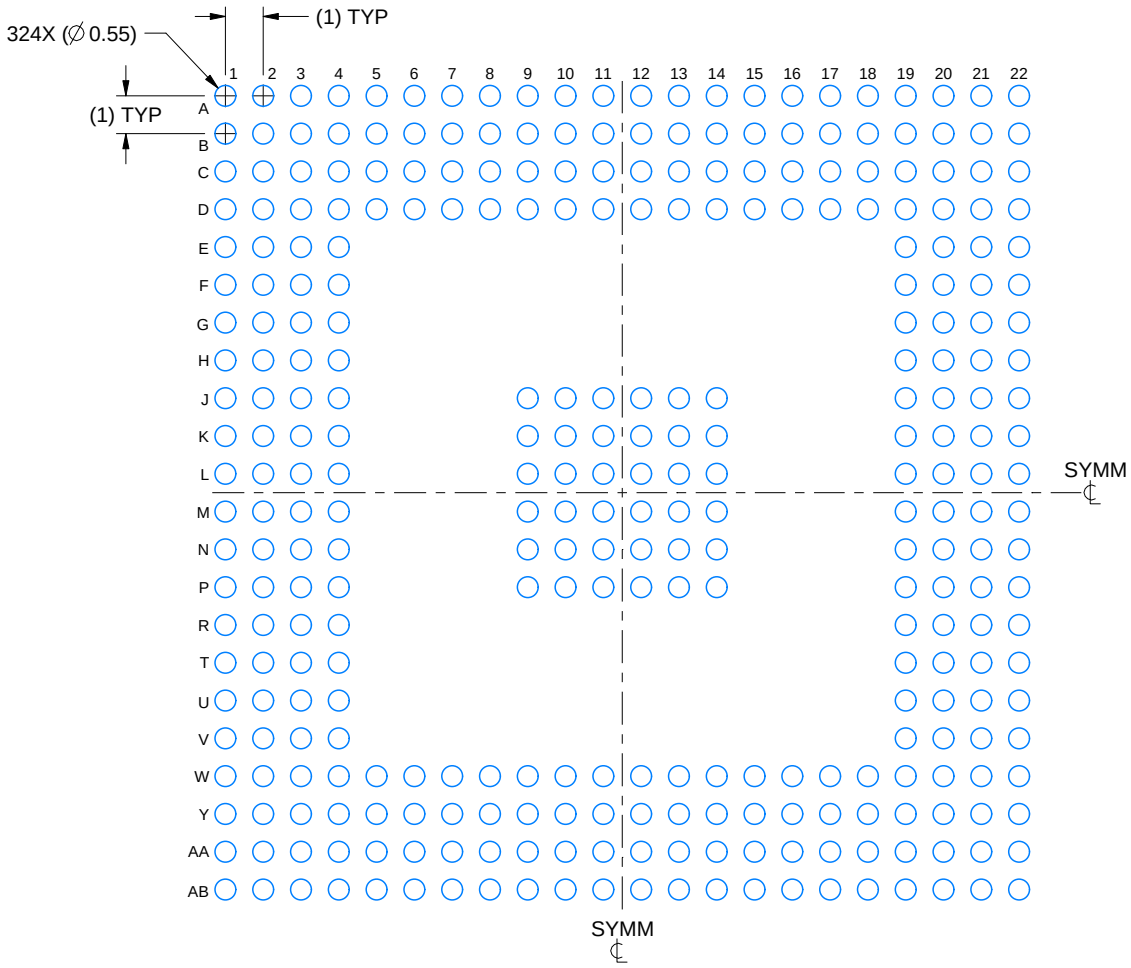
BGA - 2.352 mm max height

BALL GRID ARRAY



ALTERNATE MOLD DIMENSION	
OPT	DIM A
01	19.55
02	19.5

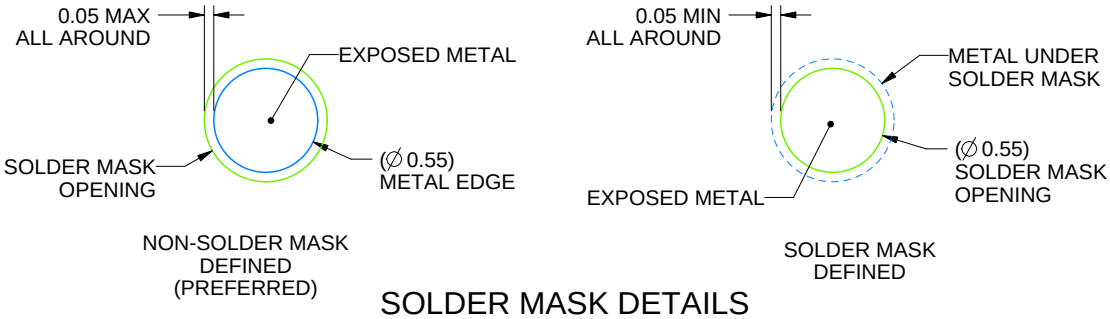
NOTES:
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Dimension is measured at the maximum solder ball diameter parallel to datum plane C.
4. Datum C (Seating Plane) is defined by the spherical crowns of the solder balls.
5. Parallesim measurement shall exclude any effect of mark on the top surface of package.



LAND PATTERN EXAMPLE

EXPOSED METAL SHOWN

SCALE: 5X



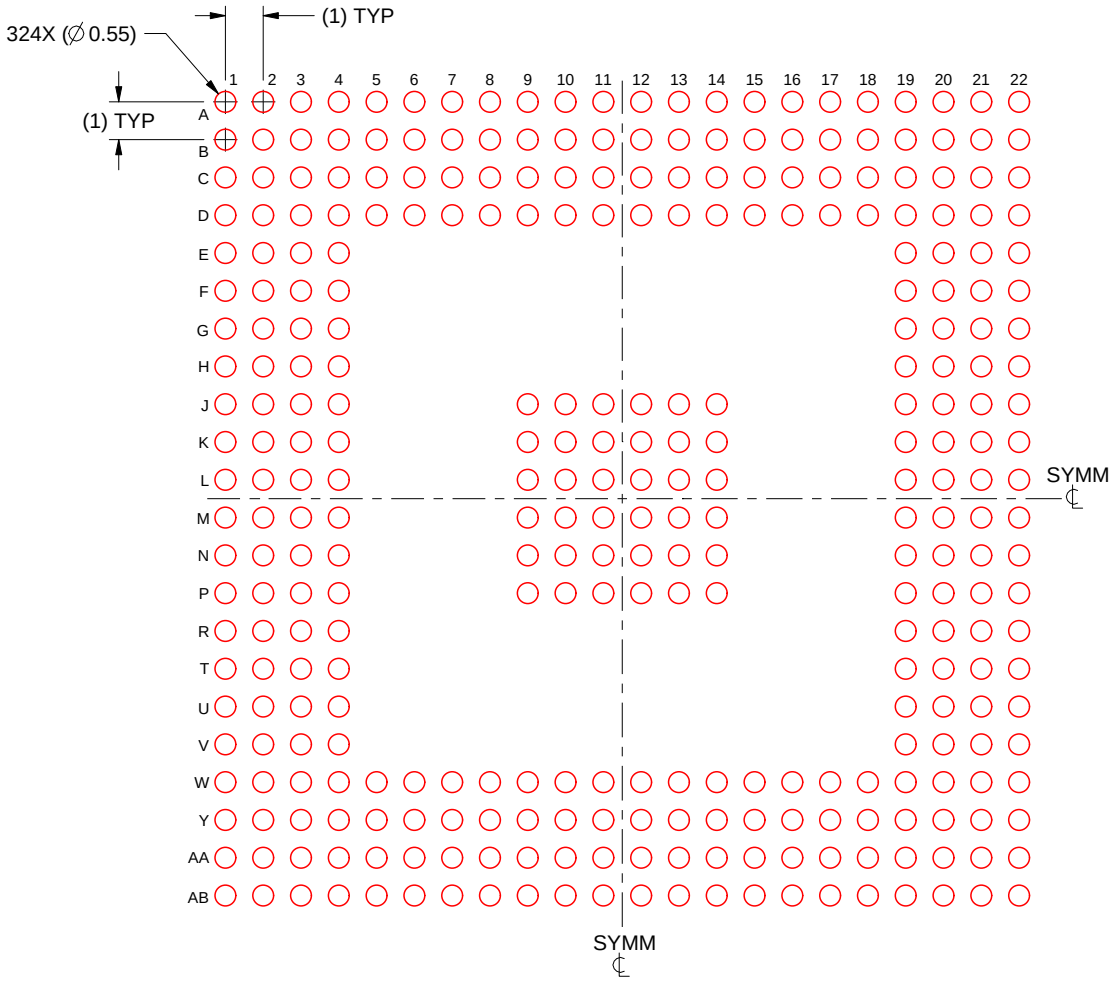
SOLDER MASK DETAILS

NOT TO SCALE

4228691/A 05/2022

NOTES: (continued)

6. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 (www.ti.com/lit/spraa99).



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 5X

4228691/A 05/2022

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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